Hi-Flow[®] 565UT

Tacky, High Performance, Un-Reinforced Phase Change Thermal Interface Material

Features and Benefits

- Thermal impedance: 0.05°C-in²/W (@25 psi)
- High thermal conductivity: 3.0 W/m-k
- Phase change softening temp 52°C
- Naturally tacky
- Tabulated for ease of assembly



Hi-Flow 565UT is a naturally tacky, thermally conductive phase change material which is supplied in an easy to use tabulated pad form. In the application the material undergoes a phase change softening, starting near 52°C. The phase change softening feature improves handling characteristics prior to assembly. At application temperatures and pressures, Hi-Flow 565UT wets out the thermal interfaces resulting in a very low thermal impedance.

The thermal performance of Hi-Flow 565UT is comparable to the best thermal greases. Hi-Flow 565UT is provided at a consistent thickness to ensure reliable performance. Hi-Flow 565UT can be applied in high volumes to the target surface via low pressure from a roller or manual application.

TYPICAL PROPERTIES OF HI-FLOW 565UT						
PROPERTY	IMPERIAL VALUE		METRIC VALUE		TEST METHOD	
Color	Blue		Blue		Visual	
Reinforcement Carrier	None		None		_	
Thickness (inch) / (mm)	0.005, 0.010		0.127, 0.254		ASTM D374	
Continuous Use Temp (°F) / (°C)	257		125		_	
Phase Change Softening Temp (°F) / (°C)	126		52		ASTM D3418	
ELECTRICAL						
Flame Rating	V-O		V-O		U.L. 94	
THERMAL						
Thermal Conductivity (W/m-K) (I)	3.0		3.0		ASTM D5470	
THERMAL PERFORMANCE vs PRESSURE						
Press	sure (psi)	10	25	50	100	200
TO-220 Thermal Performance (°C/W)		0.37	0.35	0.34	0.30	0.26
Thermal Impedance (°C-in²/W)(2)		0.09	0.05	0.03	0.02	0.02

1) This is the measured thermal conductivity of the Hi-Flow coating. It represents one conducting layer in a three-layer laminate. The Hi-Flow coatings are phase change compounds. These layers will respond to heat and pressure induced stresses. The overall conductivity of the material in post-phase change, thin film products is highly dependent upon the heat and pressure applied. This characteristic is not accounted for in ASTM D5470. Please contact Bergquist Product Management if additional specifications are required.

2) The ASTM D5470 test fixture was used and the test sample was conditioned at 70°C prior to test. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.

Typical Applications Include:

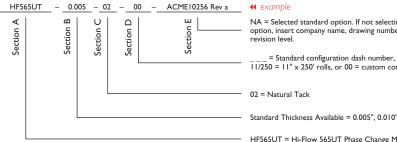
- Processor lid to heat sink
- FBDIMM to heat spreader
- Processor die to lid or heat sink

Configurations Available:

- Tabulated in roll form, kiss-cut parts no holes
- Hi-Flow 565UT is limited to a square or rectangular part design.

Building a Part Number

Standard Options



NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and

= Standard configuration dash number, 11/250 = 11" x 250' rolls, or 00 = custom configuration

HF565UT = Hi-Flow 565UT Phase Change Material

Note: To build a part number, visit our website at www.bergquistcompany.com.

Hi-Flow®: U.S. Patent 6,197,859 and others